

Claim 1 (amended). A method for producing an electrical connection between integrated circuits, which comprises:

providing a first integrated circuit having a terminal and a signal terminal;

forming an electrically conductive connection between the terminal and the signal terminal of the first integrated circuit;

*Paul D*  
providing a protective structure that becomes conductive to dissipate electrostatic discharges;

*B1*  
providing a second integrated circuit having a terminal that is coupled to [a protective structure for protecting against electrostatic discharges] the protective structure;

disposing the first and second integrated circuits adjacent one another;

electrically connecting the signal terminal of the first integrated circuit to the terminal of the second integrated circuit; [and]

connecting the terminal of the first integrated circuit to a terminal of a package; and

*D*  
*and*  
*B1*  
*and*  
subsequent to connecting the terminal of the first integrated circuit to the terminal of the package, severing the electrically conductive connection between the terminal and the signal terminal of the first integrated circuit using an energy pulse.

Claim 8 (amended). A method for producing an electrical connection between integrated circuits, which comprises:

providing a first integrated circuit having a surface;

disposing first and second terminal pads on the surface of the first integrated circuit;

*B2*  
*and*  
forming an electrically conductive connection between the first and second terminal pads of the first integrated circuit;

*and C*  
providing a second integrated circuit having a surface;

disposing first and second terminal pads on the surface of the second integrated circuit;

providing a protective structure that becomes conductive to dissipate electrostatic discharges;

electrically coupling at least the first terminal pad of the second integrated circuit to [a protective structure for protecting against electrostatic discharges] the protective structure;

disposing the surfaces of the first and second integrated circuits longitudinally adjacent one another so that the first and second terminal pads of the second integrated circuit are not covered by the first integrated circuit;

*B2*  
*and*  
*C1*  
*and*  
electrically joining at least one of the first and second terminal pads of the first integrated circuit to one of the first and second terminal pads of the second integrated circuit; and

[forming an electrically conductive connection between the first and second terminal pads of the first integrated circuit; and]

severing the electrically conductive connection using an energy pulse.

Remarks:

Reconsideration of the application is requested.